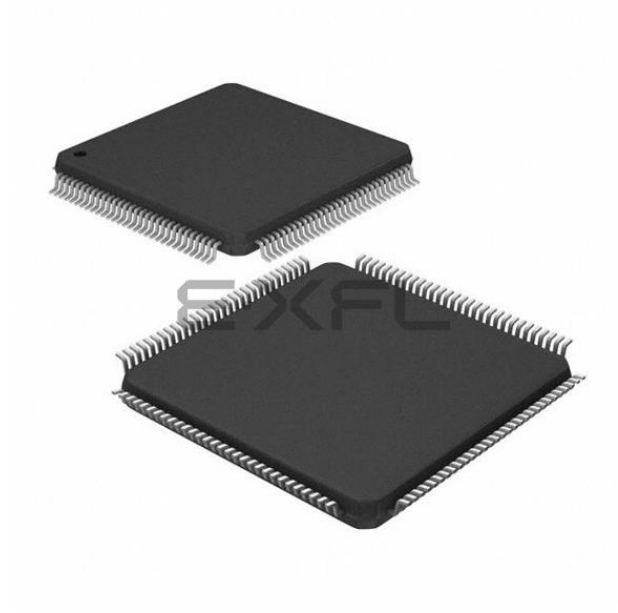
Infineon Technologies - MB90922NCSPMC-GS-233E1 Datasheet



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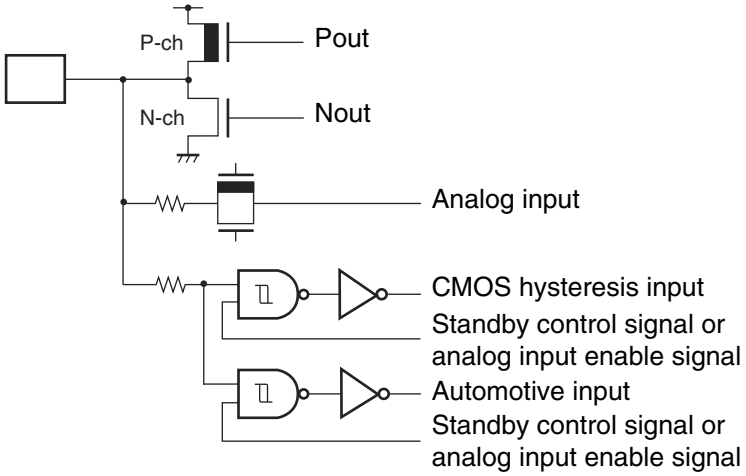
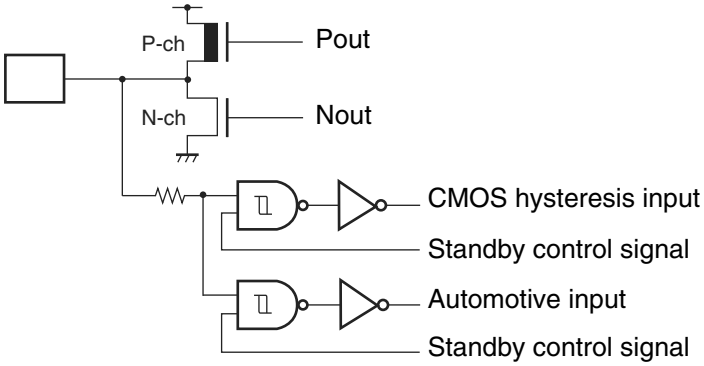
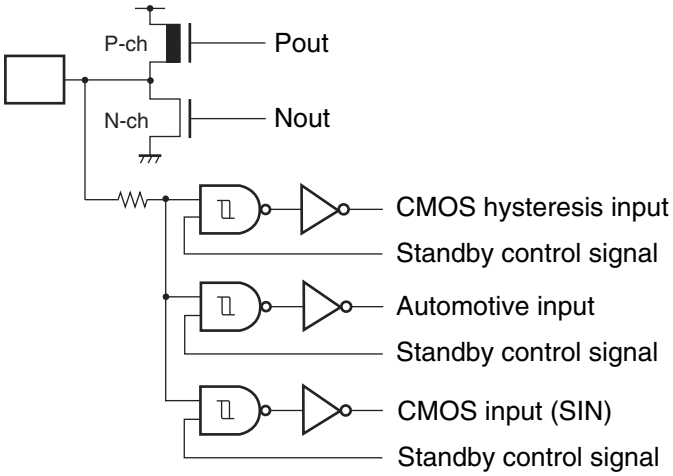
What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	F²MC-16LX
Core Size	16-Bit
Speed	32MHz
Connectivity	CANbus, LINbus, UART/USART
Peripherals	LCD, LVD, POR, PWM, WDT
Number of I/O	93
Program Memory Size	256KB (256K x 8)
Program Memory Type	Mask ROM
EEPROM Size	-
RAM Size	10K x 8
Voltage - Supply (Vcc/Vdd)	4V ~ 5.5V
Data Converters	A/D 8x8/10b
Oscillator Type	External
Operating Temperature	-40°C ~ 105°C (TA)
Mounting Type	Surface Mount
Package / Case	120-LQFP
Supplier Device Package	120-LQFP (16x16)
Purchase URL	https://www.e-xfl.com/product-detail/infineon-technologies/mb90922ncspmc-gs-233e1

Type	Circuit	Remarks
H		A/D converter input common general-purpose port • CMOS output (I_{OH}/I_{OL} = ± 4 mA) • CMOS hysteresis input (V_{IH}/V_{IL} = 0.8 V_{CC}/0.2 V_{CC}) • Automotive input (V_{IH}/V_{IL} = 0.8 V_{CC}/0.5 V_{CC})
I		General-purpose port • CMOS output (I_{OH}/I_{OL} = ± 4 mA) • CMOS hysteresis input (V_{IH}/V_{IL} = 0.8 V_{CC}/0.2 V_{CC}) • Automotive input (V_{IH}/V_{IL} = 0.8 V_{CC}/0.5 V_{CC})
J		General-purpose port (serial input) • CMOS output (I_{OH}/I_{OL} = ± 4 mA) • CMOS hysteresis input (V_{IH}/V_{IL} = 0.8 V_{CC}/0.2 V_{CC}) • CMOS input (SIN) (V_{IH}/V_{IL} = 0.7 V_{CC}/0.3 V_{CC}) • Automotive input (V_{IH}/V_{IL} = 0.8 V_{CC}/0.5 V_{CC})

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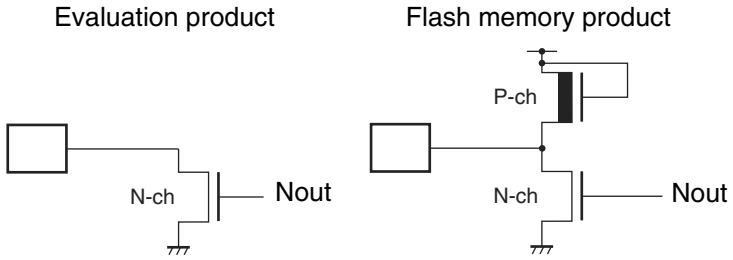
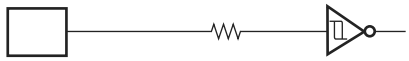
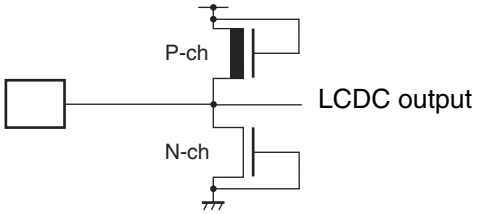
Type	Circuit	Remarks
N		N-ch open-drain pin I_{OL} = 4 mA
O		Input-only pin Automotive input (V_{IH}/V_{IL} = 0.8 V_{CC}/0.5 V_{CC})
P		LCDC output pin (COM pin)

■ HANDLING DEVICES

• Strictly observe maximum rated voltages (preventing latch-up)

In CMOS IC devices, a condition known as latch-up may occur if voltages higher than V_{CC} or lower than V_{SS} are applied to input or output pins other than medium or high withstand voltage pins, or if the voltage applied between VCC and VSS pins exceeds the rated voltage level. If a latch-up occurs, the power supply current may increase dramatically and may destroy semiconductor elements. When using semiconductor devices, always take sufficient care to avoid exceeding maximum ratings.

When the analog system power supply is switched on or off, be careful not to apply the analog power supply (AV_{CC}, AVRH), the analog input voltages and the power supply voltage for the high current output buffer pins (DV_{CC}) in excess of the digital power supply voltage (V_{CC}).

Once the digital power supply voltage (V_{CC}) has been disconnected, the analog power supply (AV_{CC}, AVRH) and the power supply voltage for the high current output buffer pins (DV_{CC}) may be turned on in any sequence.

• Supply voltage stabilization

Rapid fluctuations in the power supply voltage can cause malfunctions even if the Vcc power supply voltage remains within the warranted operating range. It is recommended that the power supply be stabilized such that ripple fluctuations (P-P value) at commercial frequencies (50 Hz/60 Hz) be limited to within 10% of the standard V_{CC} value, and that transient fluctuations due to power supply switching, etc. be limited to a rate of 0.1 V/ms or less.

• Precautions when turning the power on

In order to prevent the built-in step-down circuits from malfunctioning, the time taken for the voltage to rise (0.2 V to 2.7 V) during power-on should be less than 50 μs.

• Handling unused pins

If unused input pins are left open, they may cause malfunctions or latch-up which may lead to permanent damage to the semiconductor. Unused input pins should therefore be pulled up or pulled down through a resistor of at least 2 kΩ.

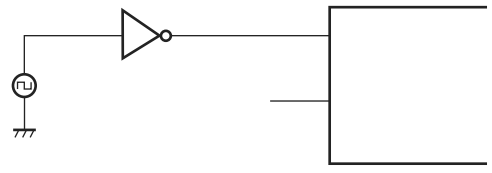
Unused input/output pins may be set to the output state and left open, or set to the input state and connected to a pull-up or pull-down resistance of 2 kΩ or more.

• Handling A/D converter power supply pins

Even if the A/D converter is not used, the power supply pins should be connected such as $AV_{CC} = V_{CC}$, and $AV_{SS} = AVRH = V_{SS}$.

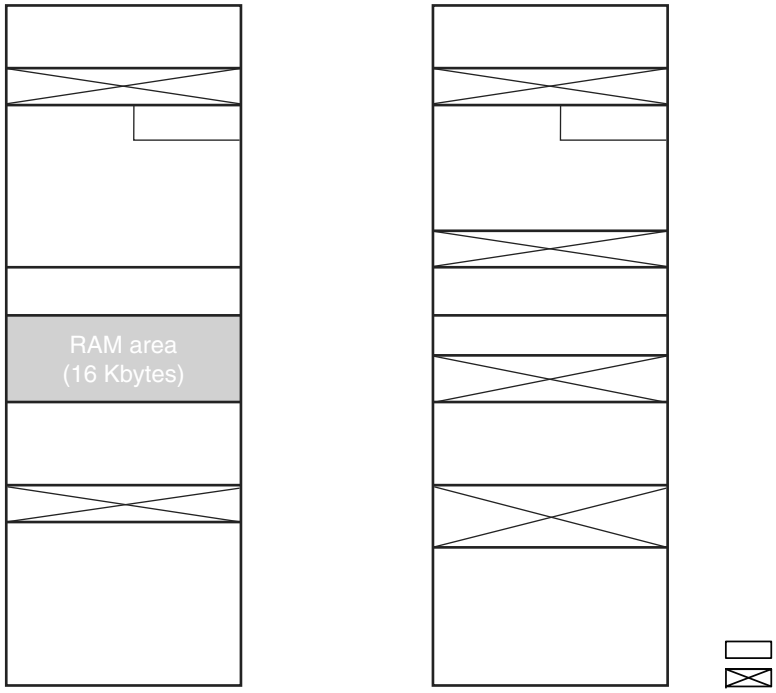
• Notes on using an external clock

Even when an external clock is used, an oscillation stabilization wait time is required following power-on reset or release from sub clock mode or stop mode. Furthermore, only the X0A pin should be driven when an external clock is used, with the X1A pin open as shown in the following diagram. Do not use high-speed oscillation pins (X0 and X1) for external clock input.



Sample external clock connection

■ MEMORY MAP



MB90F922 / MB90922
MB90F923 / MB90F924

Parts No.	ROM (Flash) capacitance	RAM capacitance	Address #1	Address #2	Address #3
MB90F922NC/F922NCS/922NCS	256 Kbytes	10 Kbytes	FC0000H	004000H	002900H
MB90F923NC/F923NCS	384 Kbytes	16 Kbytes	FA0000H	004A00H	003700H
MB90F924NC/F924NCS	512 Kbytes	24 Kbytes	F80000H	006A00H	003700H

* : Evaluation products do not contain internal ROM. Treat this address as the ROM decode area used by the tools.

Note: To select models without the ROM mirror function, refer to the “ROM Mirror Function Selection Module” in Hardware Manual. The image of the ROM data in the FF bank appears at the top of the 00 bank, in order to enable efficient use of small C compiler models. The lower 16-bits of the FF bank addresses are allocated to the same addresses as the lower 16-bits of the 00 bank, making it possible to reference tables in ROM without declaring the “far” modifier with the pointers. For example, when an access is made to the address 00C000H, the actual address to be accessed is FFC000H in ROM. Because the size of the FF bank ROM area exceeds 32 Kbytes, it is not possible to view the entire region in the 00 bank image. Therefore because the ROM data from FF8000H to FFFFFFH appears in the image from 008000H to 00FFFFH, it is recommended that ROM data tables be stored in the area from FF8000H to FFFFFFH.

Address	Register name	Symbol	Read/write	Resource name	Initial value
000024H	Compare clear register	CPCLR	R/W	16-bit free-run timer	XXXXXXXXB
000025H			R/W		XXXXXXXXB
000026H	Timer data register	TCDT	R/W		00000000B
000027H			R/W		00000000B
000028H	Lower timer control status register	TCCSL	R/W		00000000B
000029H	Higher timer control status register	TCCSH	R/W		01-00000B
00002AH	Lower PPG0 control status register	PCNTL0	R/W	16-bit PPG0	00000000B
00002BH	Higher PPG0 control status register	PCNTH0	R/W		00000001B
00002CH	Lower PPG1 control status register	PCNTL1	R/W	16-bit PPG1	00000000B
00002DH	Higher PPG1 control status register	PCNTH1	R/W		00000001B
00002EH	Lower PPG2 control status register	PCNTL2	R/W	16-bit PPG2	00000000B
00002FH	Higher PPG2 control status register	PCNTH2	R/W		00000001B
000030H	External interrupt enable	ENIR	R/W	External interrupt	00000000B
000031H	External interrupt request	EIRR	R/W		00000000B
000032H	Lower external interrupt level	ELVRL	R/W		00000000B
000033H	Higher external interrupt level	ELVRH	R/W		00000000B
000034H	Serial mode register 0	SMR0	R/W, W	UART (LIN/SCI) 0	00000000B
000035H	Serial control register 0	SCR0	R/W, W		00000000B
000036H	Reception/transmission data register 1	RDR0/ TDR0	R/W		00000000B
000037H	Serial status register 0	SSR0	R/W, R		00001000B
000038H	Extended communication control register 0	ECCR0	R/W, R		000000XXB
000039H	Extended status control register 0	ESCR0	R/W		00000100B
00003AH	Baud rate generator register 00	BGR00	R/W		00000000B
00003BH	Baud rate generator register 01	BGR01	R/W, R		00000000B
00003CH to 00003FH	(Disabled)				
000040H to 00004FH	Area reserved for CAN Controller 0. Refer to "■ CAN CONTROLLERS"				
000050H	Lower timer control status register 0	TMCSR0L	R/W	16-bit reload timer 0	00000000B
000051H	Higher timer control status register 0	TMCSR0H	R/W		XXX10000B
000052H	Timer register 0/reload register 0	TMR0/ TMRLR0	R/W		XXXXXXXXB
000053H					XXXXXXXXB

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Address	Register name	Symbol	Read/write	Resource name	Initial value
003998H	PWM1 compare register 3	PWC13	R/W	Stepping motor controller 3	XXXXXXXXB
003999H					XXXXXXXXB
00399AH	PWM2 compare register 3	PWC23	R/W		XXXXXXXXB
00399BH					XXXXXXXXB
00399CH	PWM1 select register 3	PWS13	R/W		00000000B
00399DH	PWM2 select register 3	PWS23	R/W		X0000000B
00399EH to 0039A5H	(Disabled)				
0039A6H	Flash write control register 0	FWR0	R/W	Flash I/F	00000000B
0039A7H	Flash write control register 1	FWR1			00000000B
0039A8H to 0039BFH	(Disabled)				
0039C0H to 0039DFH	Area reserved for CAN Controller 2. Refer to “■ CAN CONTROLLERS”				
0039E0H to 0039FFH	Area reserved for CAN Controller 3. Refer to “■ CAN CONTROLLERS”				
003A00H to 003AFFH	Area reserved for CAN Controller 0. Refer to “■ CAN CONTROLLERS”				
003B00H to 003BFFH	Area reserved for CAN Controller 1. Refer to “■ CAN CONTROLLERS”				
003C00H to 003CFFH	Area reserved for CAN Controller 0. Refer to “■ CAN CONTROLLERS”				
003D00H to 003DFFH	Area reserved for CAN Controller 1. Refer to “■ CAN CONTROLLERS”				
003E00H to 003EFFH	Area reserved for CAN Controller 2. Refer to “■ CAN CONTROLLERS”				
003F00H to 003FFFH	Area reserved for CAN Controller 3. Refer to “■ CAN CONTROLLERS”				

List of Message Buffers (ID Registers)

Address				Register	Abbre-viation	Access	Initial Value
CAN0	CAN1	CAN2	CAN3				
003A00H to 003A1FH	003B00H to 003B1FH	003700H to 00371FH	003800H to 00381FH	General-purpose RAM	—	R/W	XXXXXXXXB to XXXXXXXXB
003A20H	003B20H	003720H	003820H	ID register 0	IDR0	R/W	XXXXXXXXB XXXXXXXXB
003A21H	003B21H	003721H	003821H				
003A22H	003B22H	003722H	003822H				XXXXX---B XXXXXXXXB
003A23H	003B23H	003723H	003823H				
003A24H	003B24H	003724H	003824H	ID register 1	IDR1	R/W	XXXXXXXXB XXXXXXXXB
003A25H	003B25H	003725H	003825H				
003A26H	003B26H	003726H	003826H				XXXXX---B XXXXXXXXB
003A27H	003B27H	003727H	003827H				
003A28H	003B28H	003728H	003828H	ID register 2	IDR2	R/W	XXXXXXXXB XXXXXXXXB
003A29H	003B29H	003729H	003829H				
003A2AH	003B2AH	00372AH	00382AH				XXXXX---B XXXXXXXXB
003A2BH	003B2BH	00372BH	00382BH				
003A2CH	003B2CH	00372CH	00382CH	ID register 3	IDR3	R/W	XXXXXXXXB XXXXXXXXB
003A2DH	003B2DH	00372DH	00382DH				
003A2EH	003B2EH	00372EH	00382EH				XXXXX---B XXXXXXXXB
003A2FH	003B2FH	00372FH	00382FH				
003A30H	003B30H	003730H	003830H	ID register 4	IDR4	R/W	XXXXXXXXB XXXXXXXXB
003A31H	003B31H	003731H	003831H				
003A32H	003B32H	003732H	003832H				XXXXX---B XXXXXXXXB
003A33H	003B33H	003733H	003833H				
003A34H	003B34H	003734H	003834H	ID register 5	IDR5	R/W	XXXXXXXXB XXXXXXXXB
003A35H	003B35H	003735H	003835H				
003A36H	003B36H	003736H	003836H				XXXXX---B XXXXXXXXB
003A37H	003B37H	003737H	003837H				
003A38H	003B38H	003738H	003838H	ID register 6	IDR6	R/W	XXXXXXXXB XXXXXXXXB
003A39H	003B39H	003739H	003839H				
003A3AH	003B3AH	00373AH	00383AH				XXXXX---B XXXXXXXXB
003A3BH	003B3BH	00373BH	00383BH				
003A3CH	003B3CH	00373CH	00383CH	ID register 7	IDR7	R/W	XXXXXXXXB XXXXXXXXB
003A3DH	003B3DH	00373DH	00383DH				
003A3EH	003B3EH	00373EH	00383EH				XXXXX---B XXXXXXXXB
003A3FH	003B3FH	00373FH	00383FH				

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3. DC Characteristics

(V_{CC} = 5.0 V ±10%, V_{SS} = DV_{SS} = AV_{SS} = 0.0 V, T_A = − 40 °C to +105 °C)

Parameter	Symbol	Pin name	Conditions	Value			Unit	Remarks
				Min	Typ	Max		
"H" level input voltage	V_{IHA}	—	—	0.8 V_{CC}	—	—	V	Pin inputs if Automotive input levels are selected
	V_{IHS}	—	—	0.8 V_{CC}	—	—	V	Pin inputs if CMOS hysteresis input levels are selected
	V_{IHC}	—	—	0.7 V_{CC}	—	—	V	$\overline{RST}$ input pin (CMOS hysteresis)
"L" level input voltage	V_{ILA}	—	—	—	—	0.5 V_{CC}	V	Pin inputs if Automotive input levels are selected
	V_{ILS}	—	—	—	—	0.2 V_{CC}	V	Pin inputs if CMOS hysteresis input levels are selected
	V_{ILR}	—	—	—	—	0.3 V_{CC}	V	$\overline{RST}$ input pin (CMOS hysteresis)
Power supply current*	I_{CC}	V_{CC}	Maximum operating frequency F_{CP} = 32 MHz, normal operation	—	35	45	mA	
			Maximum operating frequency F_{CP} = 32 MHz, writing Flash memory	—	55	65	mA	
	I_{CCS}		Operating frequency F_{CP} = 32 MHz, sleep mode	—	13	20	mA	
	I_{CTS}		Operating frequency F_{CP} = 2 MHz, time-base timer mode	—	0.6	1.0	mA	
	I_{CTSPLL}		Operating frequency F_{CP} = 32 MHz, PLL timer mode, External frequency = 4 MHz	—	2.5	4	mA	
	I_{CCL}		Operating frequency F_{CP} = 8 kHz, T_A = + 25 °C, sub clock operation	—	120	270	µA	
	I_{CCLS}		Operating frequency F_{CP} = 8 kHz, T_A = + 25 °C, sub sleep operation	—	100	200	µA	
	I_{CCT}		Operating frequency F_{CP} = 8 kHz, T_A = + 25 °C, watch mode	—	90	180	µA	
	I_{CCH}		T_A = + 25 °C, stop mode	—	80	170	µA	

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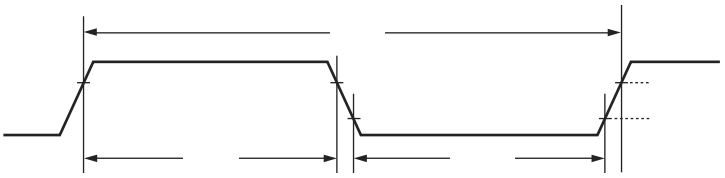
(V_{CC} = 5.0 V ±10%, V_{SS} = DV_{SS} = AV_{SS} = 0.0 V, T_A = − 40 °C to +105 °C)

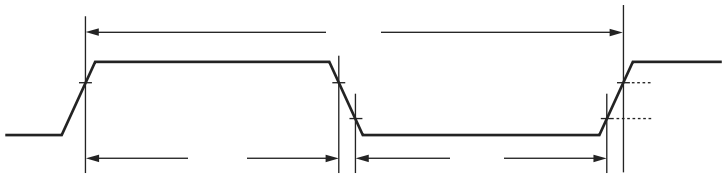
Parameter	Symbol	Pin name	Conditions	Value			Unit	Remarks
				Min	Typ	Max		
LCDC leakage current	I_{LCDC}	V0 to V3, COMm (m = 0 to 3) , SEGn, (n = 00 to 31)	—	—	—	5.0	µA	
LCD output impedance	Rvcom	COMn (n = 0 to 3)	—	—	—	4.5	kΩ	
	Rvseg	SEGn (n = 00 to 31)	—	—	—	17	kΩ	

* : Power supply current values assume an external clock supplied to the X1 pin and X1A pin. Users must be aware that power supply current levels differ depending on whether an external clock or oscillator is used.

• X0, X1 clock timing



• X0A, X1A clock timing



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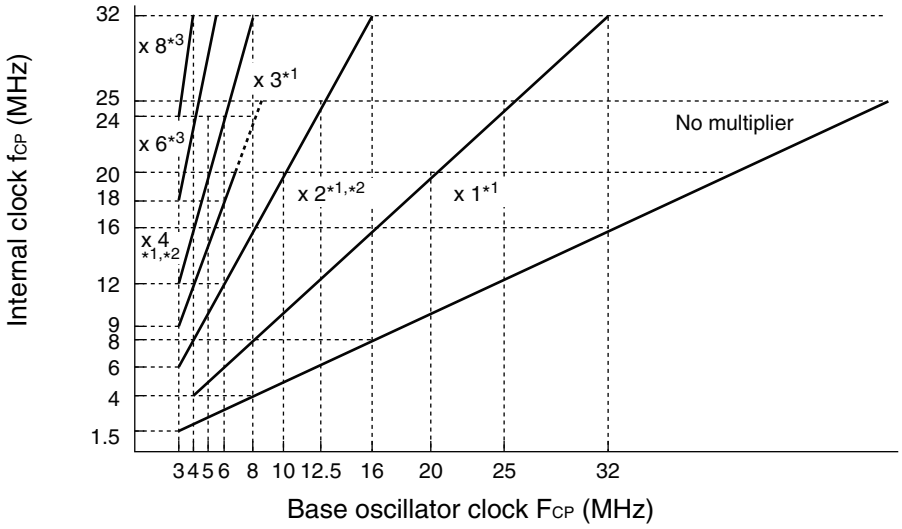
Base oscillator frequency vs. Internal operating clock frequency



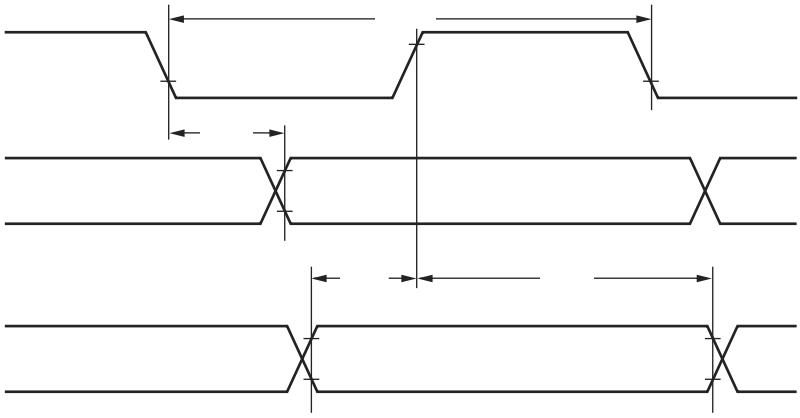
*1 : When the PLL multiplier is × 1, × 2, × 3 or × 4 and the internal clock is 20 MHz < f_{CP} ≤ 32 MHz, set DIV2 bit = "1"*4, CS2 bit = "1" in the PSCCR register.
[Example] When using a base oscillator frequency of 24 MHz at PLL × 1 :
CKSCR register : CS1 bit = "0", CS0 bit = "0"
PSCCR register : DIV2 bit = "1"*4,CS2 bit = "1"
[Example] When using a base oscillator frequency of 6 MHz at PLL × 3 :
CKSCR register : CS1 bit = "1", CS0 bit = "0"
PSCCR register : DIV2 bit = "1"*4, CS2 bit = "1"

*2 : When the PLL multiplier is × 2 or × 4 and the internal clock is 20 MHz < f_{CP} ≤ 32 MHz, the following settings are also supported.
PLL × 2 : CKSCR register : CS1 bit = "0", CS0 bit = "0"
PSCCR register : DIV2 bit = "0"*4, CS2 bit = "0"
PLL × 4 : CKSCR register : CS1 bit = "0", CS0 bit = "1"
PSCCR register : DIV2 bit = "0"*4, CS2 bit = "0"

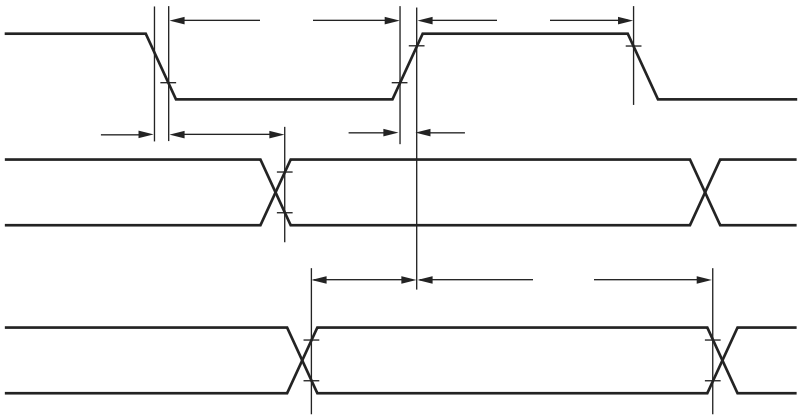
*3 : When the PLL multiplier is set to × 6 or × 8 set "DIV2 bit = "0"*4 CS2 bit = "1" and "PLL2 bit = 1" in the PSCCR register.
[Example] When using a base oscillator frequency of 4 MHz at PLL × 6 :
CKSCR register : CS1 bit = "1", CS0 bit = "0"
PLLOS register : DIV2 bit = "0"*4, CS2 bit = "1"
[Example] When using a base oscillator frequency of 3 MHz at PLL × 8 :
CKSCR register : CS1 bit = "1", CS0 bit = "1"
PLLOS register : DIV2 bit = "0"*4, CS2 bit = "1"

*4 : The DIV2 bit is assigned to bit 9 of the PSCCR register and the CS2 bit is assigned to bit 8 of the PSCCR register. Both bits have a default value of "0".

- Internal shift clock mode



- External shift clock mode



• **Bit setting: ESCR0/1/2/3:SCES=1, ECCR0/1/2/3:SCDE=0**

(V_{CC} = 5.0 V±10%, V_{SS} = AV_{SS} = 0.0 V, T_A = − 40 °C to +105 °C)

Parameter	Symbol	Pin name	Conditions	Value		Unit
				Min	Max	
Serial clock cycle time	t_{SCYC}	SCK0 to SCK3	Internal shift clock mode output pin C_L = 80 pF + 1TTL	5 t_{CP}	—	ns
SCK ↑ → SOT delay time	t_{SHOVI}	SCK0 to SCK3, SOT0 to SOT3		− 50	+ 50	ns
Valid SIN → SCK ↓	t_{IVSLI}	SCK0 to SCK3, SIN0 to SIN3		t_{CP} + 80	—	ns
SCK ↓ → valid SIN hold time	t_{SLIXI}			0	—	ns
Serial clock “H” pulse width	t_{SHSL}	SCK0 to SCK3	External shift clock mode output pin C_L = 80 pF + 1TTL	3 t_{CP} − t_R	—	ns
Serial clock “L” pulse width	t_{SLSH}			t_{CP} + 10	—	ns
SCK ↑ → SOT delay time	t_{SHOVE}	SCK0 to SCK3, SOT0 to SOT3		—	2 t_{CP} + 60	ns
Valid SIN → SCK ↓	t_{IVSLE}	SCK0 to SCK3, SIN0 to SIN3		30	—	ns
SCK ↓ → valid SIN hold time	t_{SLIXE}			t_{CP} + 30	—	ns
SCK ↓ time	t_F	SCK0 to SCK3		—	10	ns
SCK ↑ time	t_R			—	10	ns

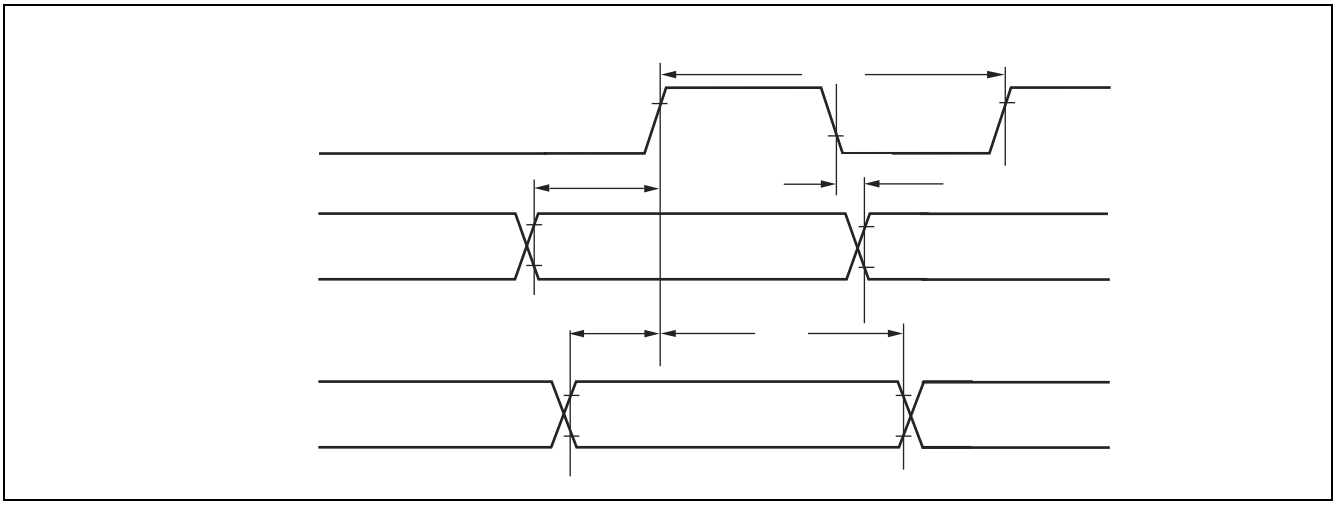
Notes : • Depending on the machine clock frequency to be used, the maximum baud rate may be limited by some parameters. These parameters are shown in “MB90920 series hardware manual”.
• C_L is the load capacitance connected to the pin during testing.
• t_{CP} is the internal operating clock cycle time. Refer to “ (1) Clock timing”.

• **Bit setting: ESCR0/1/2/3:SCES=1, ECCR0/1/2/3:SCDE=1**

(V_{CC} = 5.0 V±10%, V_{SS} = AV_{SS} = 0.0 V, T_A = –40 °C to +105 °C)

Parameter	Symbol	Pin name	Conditions	Value		Unit
				Min	Max	
Serial clock cycle time	t_{SCYC}	SCK0 to SCK3	Internal shift clock mode output pin C_L = 80 pF + 1TTL	5 t_{CP}	—	ns
SCK ↓ → SOT delay time	t_{SLOVI}	SCK0 to SCK3, SOT0 to SOT3		– 50	+ 50	ns
Valid SIN → SCK ↓	t_{IVSHI}	SCK0 to SCK3, SIN0 to SIN3		t_{CP} + 80	—	ns
SCK ↑ → valid SIN hold time	t_{SHIXI}			0	—	ns
SOT → SCK ↑ delay time	t_{SOVHI}	SCK0 to SCK3, SOT0 to SOT3		3 t_{CP} – 70	—	ns

Notes :
- Depending on the machine clock frequency to be used, the maximum baud rate may be limited by some parameters. These parameters are shown in “MB90920 series hardware manual”.
- C_L is the load capacitance connected to the pin during testing.
- t_{CP} is the internal operating clock cycle time. Refer to “ (1) Clock timing”.



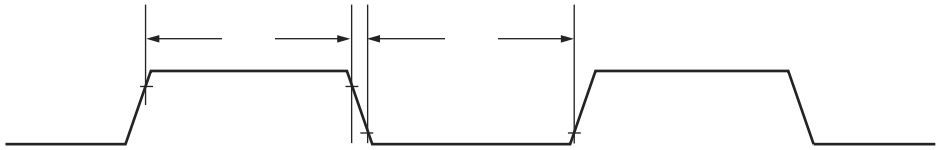
(5) Timer input timing

(V_{CC} = 5.0 V±10%, V_{SS} = AV_{SS} = 0.0 V, T_A = –40 °C to +105 °C)

Parameter	Symbol	Pin name	Conditions	Value		Unit
				Min	Max	
Input pulse width	t_{TIWH} t_{TIWL}	TIN0, TIN1, IN0 to IN3	—	4 t_{CP}	—	ns

Note : t_{CP} is the internal operating clock cycle time. Refer to " (1) Clock timing".

- Timer input timing



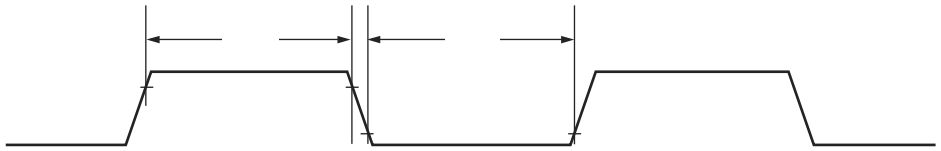
(6) Trigger input timing

(V_{CC} = 5.0 V±10%, V_{SS} = AV_{SS} = 0.0 V, T_A = –40 °C to +105 °C)

Parameter	Symbol	Pin name	Conditions	Value		Unit	Remarks
				Min	Max		
Input pulse width	t_{TRGH}, t_{TRGL}	INT0 to INT7	—	200	—	ns	During normal operation
		ADTG	—	t_{CP} + 200	—	ns	

Note : t_{CP} is the internal operating clock cycle time. Refer to “ (1) Clock timing”.

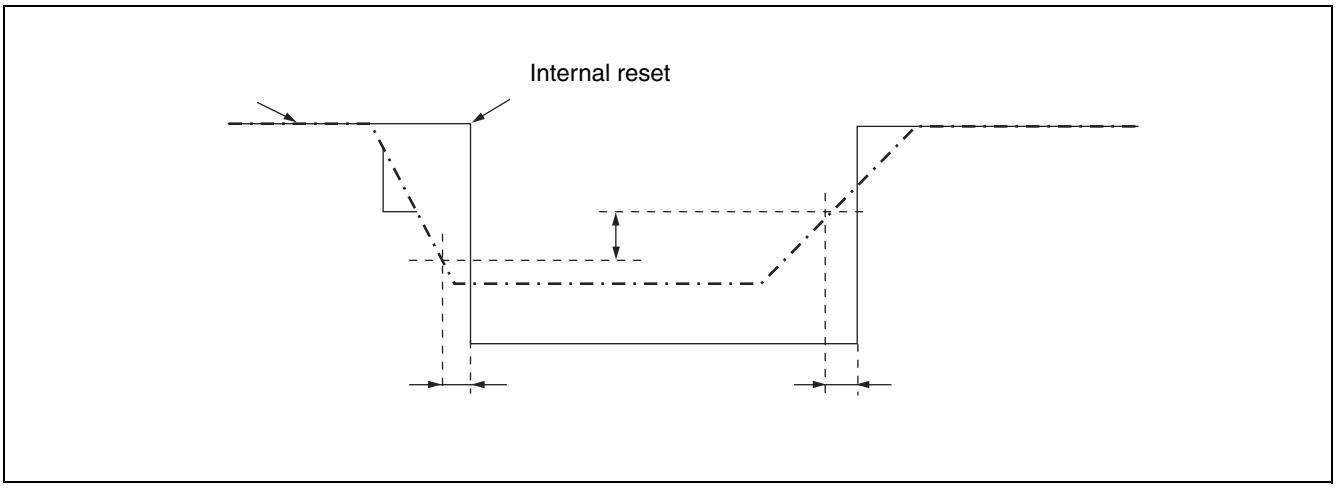
- Trigger input timing



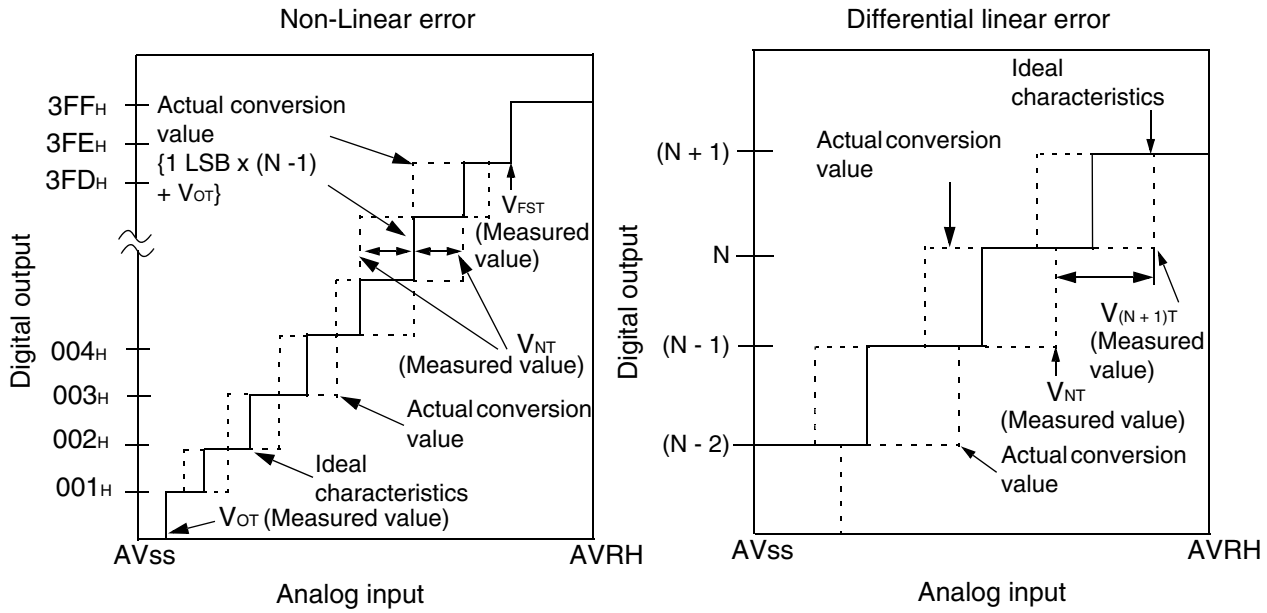
(7) Low voltage detection

(V_{SS} = AV_{SS} = 0.0 V, T_A = –40 °C to +105 °C)

Parameter	Symbol	Pin name	Conditions	Value			Unit	Remarks
				Min	Typ	Max		
Detection voltage	V_{DL}	VCC	—	4.0	4.2	4.4	V	Flash memory product, during voltage drop
				3.7	4.0	4.3	V	Evaluation product, during voltage drop
Hysteresis width	V_{HYS}	VCC	—	190	—	—	mV	Flash memory product, during voltage rise
				0.1	—	—	V	Evaluation product, during voltage rise
Power supply voltage change rate	dV/dt	VCC	—	– 0.1	—	+ 0.1	V/µs	Flash memory product, dV/dt at low voltage reset
				–0.004	—	+ 0.004	V/µs	Flash memory product, dV/dt at standard value of low voltage detection/release voltage
				– 0.1	—	+ 0.02	V/µs	Evaluation product
Detection delay time	td	—	—	—	—	3.2	µs	Flash memory product, when dV/dt ≤ 0.004 V/µs
				—	—	35	µs	Evaluation product



(Continued)



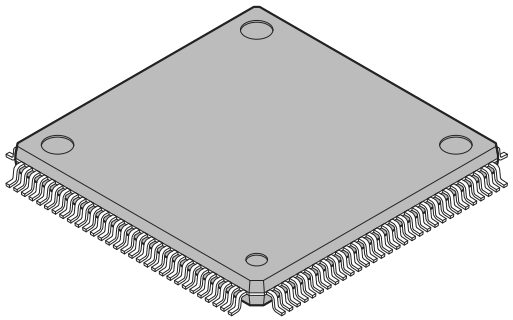
$$\text{Non-linear error of digital output N} = \frac{V_{NT} - \{1\ \text{LSB} \times (N - 1) + V_{OT}\}}{1\ \text{LSB}}\ \text{[LSB]}$$

$$\text{Differential linear error of digital output N} = \frac{V_{(N+1)T} - V_{NT}}{1\ \text{LSB}} - 1\ \text{[LSB]}$$

$$1\ \text{LSB} = \frac{V_{FST} - V_{OT}}{1022}\ \text{[V]}$$

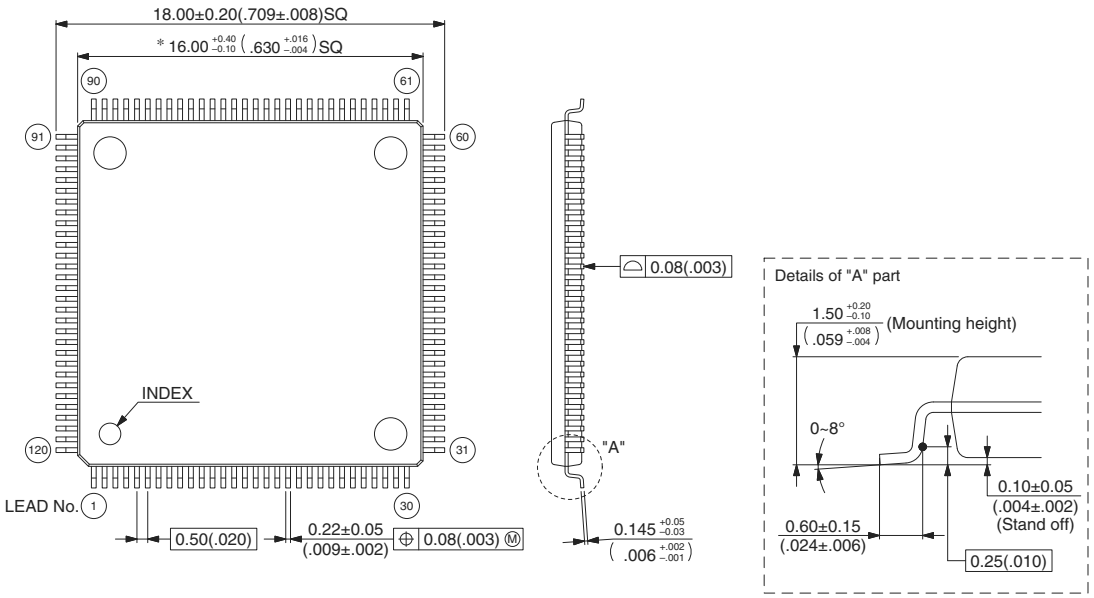
N : A/D converter digital output value
V_{OT} : Voltage when digital output changes from 000_H to 001_H
V_{FST} : Voltage when digital output changes from $3FE_H$ to $3FF_H$

■ PACKAGE DIMENSION

120-pin plastic LQFP		
	Lead pitch	0.50 mm
	Package width × package length	16.0 × 16.0 mm
	Lead shape	Gullwing
	Sealing method	Plastic mold
	Mounting height	1.70 mm MAX
	Weight	0.88 g
(FPT-120P-M21)	Code (Reference)	P-LFQFP120-16×16-0.50

120-pin plastic LQFP
(FPT-120P-M21)

Note 1) * : These dimensions do not include resin protrusion.
Resin protrusion is +0.25(.010) MAX(each side).
Note 2) Pins width and pins thickness include plating thickness.
Note 3) Pins width do not include tie bar cutting remainder.



Dimensions in mm (inches).
Note: The values in parentheses are reference values.

Please check the latest package dimension at the following URL.
http://edevice.fujitsu.com/package/en-search/

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